IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

- 1. (Currently amended) A field emission tip, comprising a structure comprising at least one of semiconductive material and conductive material, the structure including:
 - a <u>central region including a</u> periphery with an at least a substantially vertical sidewall portion;
 - a tapered and an inclined sidewall-portion surrounding the central region and including an inclined surface extending toward an exposed end of the central regionsubstantially vertical sidewall portion; and

an apex at the topexposed end of the central regionstructure.

- 2. (Currently amended) The field emission tip of claim 1, wherein a height of the at least substantially vertical sidewall portion exceeds a width of the central regionstructure.
- 3. (Previously presented) The field emission tip of claim 1, wherein the apex comprises a low work function material.
- 4. (Previously presented) The field emission tip of claim 3, wherein the low work function material is selected from the group comprising aluminum titanium silicide, titanium silicide nitride, titanium nitride, tri-chromium mono-silicon, and tantalum nitride.
- 5. (Previously presented) The field emission tip of claim 1, wherein the apex has a lateral width of less than about 100 nm.
- 6. (Previously presented) The field emission tip of claim 1, wherein the apex has a lateral width of less than about 50 nm.

- 7. (Currently amended) A field emission tip, comprising a structure comprising at least one of semiconductive material and conductive material, the structure including:

 a central region including a periphery with an at least a substantially vertical portion; and an tapered portion including an inclined surface that extends toward an exposed end of the central region, sidewall portion the tapered portion surrounding the substantially vertical sidewall portion; and an apex at the topexposed end of the structure central region, the apex having a lateral width of less than about 100 nm.
- 8. (Previously presented) The field emission tip of claim 7, wherein the apex has a lateral width of less than about 50 nm.
- 9. (Previously presented) The field emission tip of claim 7, wherein the apex comprises a low work function material.
- 10. (Previously presented) The field emission tip of claim 9, wherein the low work function material is selected from the group comprising aluminum titanium silicide, titanium silicide nitride, titanium nitride, tri-chromium mono-silicon, and tantalum nitride.
- 11. (Currently amended) A field emission array, comprising: a substrate; and
- at least one substantially pointed tip protruding from the substrate, the at least one substantially pointed tip comprising at least one of a semiconductive material and a conductive material, the at least one substantially pointed tip including a periphery, at least a first portion of the periphery being oriented substantially perpendicularly relative to the substrate and at least a second portion at an end of the at least one substantially pointed tip of the periphery being oriented at an angle relative to the substrate to form an apex; and

- at least one surrounding element including a surface that tapers toward an exposed end of the at least one substantially pointed tip and that surrounds at least a portion of the at least one substantially pointed tip, with the first portion surrounded by the second portion.
- 12. (Previously presented) The field emission array of claim 11, wherein at least the portion of the periphery is adjacent the substrate.
- 13. (Previously presented) The field emission array of claim 11, wherein a height of at least the portion of the periphery relative to the substrate exceeds a width of the at least one substantially pointed tip.
- 14. (Currently amended) The field emission array of claim 11, wherein thea top portion of the at least one substantially pointed tip comprises a low work function material.
- 15. (Previously presented) The field emission array of claim 14, wherein the low work function material is selected from the group comprising aluminum titanium silicide, titanium silicide nitride, titanium nitride, tri-chromium mono-silicon, and tantalum nitride.
- 16. (Currently amended) The field emission array of claim 11, further comprising wherein the at least one surrounding element comprises redeposition material adjacent to at least a-the first portion of the periphery.
- 17. (Previously presented) The field emission array of claim 11, wherein an apex of the at least one substantially pointed tip has a lateral width of less than about 100 nm.
- 18. (Previously presented) The field emission array of claim 11, wherein an apex of the at least one substantially pointed tip has a lateral width of less than about 50 nm.

- 19. (Currently amended) A field emission display, comprising: an anode display screen;
- a cathode spaced apart from the anode display screen, the cathode including:
 - a substrate;
 - at least one substantially pointed tip protruding from the substrate, the at least one substantially pointed tip comprising at least one of a semiconductive material and a conductive material, the at least one substantially pointed tip including a periphery, at least a first portion of the periphery being oriented substantially perpendicularly relative to the substrate and at least a second portion of the periphery being oriented at an angle relative to the substrate—with the first portion surrounded by the second portion;
 - at least one surrounding element that tapers toward an exposed end of the at least one
 substantially pointed tip and that surrounds at least a portion of the at least one
 substantially pointed tip; and
- a gate through which the at least one substantially pointed tip is exposed;
 a substantial vacuum between the anode display screen and the cathode; and
 a voltage source associated with the anode display screen, the gate, and the cathode to provide a
 potential difference between the cathode and the gate and between the cathode and the
 anode display screen.
- 20. (Currently amended) The field emission display of claim 19, wherein at least the <u>first</u> portion of the periphery is adjacent the substrate.
- 21. (Currently amended) The field emission display of claim 19, wherein a height of at least the <u>first</u> portion of the periphery relative to the substrate exceeds a width of the at least one substantially pointed tip.
- 22. (Previously presented) The field emission display of claim 19, wherein a top portion of the at least one substantially pointed tip comprises a low work function material.

- 23. (Previously presented) The field emission display of claim 22, wherein the low work function material is selected from the group comprising aluminum titanium silicide, titanium silicide nitride, titanium nitride, tri-chromium mono-silicon, and tantalum nitride.
- 24. (Currently amended) The field emission display of claim 19, wherein the at least one surrounding element comprises further comprising redeposition material adjacent to at least a the first portion of the periphery.
- 25. (Previously presented) The field emission display of claim 19, wherein an apex of the at least one substantially pointed tip has a diameter of less than about 100 nm.
- 26. (Previously presented) The field emission display of claim 19, wherein an apex of the at least one substantially pointed tip has a diameter of less than about 50 nm.